



## Material Content Data Sheet



Sales Product Name	BSZ0907ND			Issued		29. August 2013		
MA#	MA000987406							
Package	PG-WISON-8-1			Weight*		23.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.016	0.07		670	
	noble metal	gold	7440-57-5	0.060	0.26		2599	
	inorganic material	silicon	7440-21-3	0.315	1.36	1.69	13593	16862
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		124	
	non noble metal	zinc	7440-66-6	0.012	0.05		498	
	non noble metal	iron	7439-89-6	0.230	1.00		9956	
	non noble metal	copper	7440-50-8	9.354	40.43	41.49	404252	414830
wire	non noble metal	copper	7440-50-8	0.303	1.31	1.31	13076	13076
encapsulation	organic material	carbon black	1333-86-4	0.025	0.11		1073	
	plastics	epoxy resin	-	1.278	5.52		55247	
	inorganic material	silicondioxide	60676-86-0	11.109	47.99	53.62	480061	536381
leadfinish	non noble metal	tin	7440-31-5	0.360	1.56	1.56	15565	15565
plating	noble metal	silver	7440-22-4	0.076	0.33	0.33	3286	3286
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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